

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-16. (Cancelled)

17. (Currently amended) A composite structure comprising, in order:

a substrate;

a polymeric layer including a first polymeric material selected from the group consisting of polyimides, polyolefins, polyepoxides, polyurethanes, and polycarbonates;

a layer consisting essentially of silicon-oxide-containing layer; and

an added layer including a second polymeric material selected from the group consisting of polyimides, polyolefins, polyepoxides, polyurethanes, and polycarbonates.

18. (Original) The structure of claim 17 in which the first polymeric material is a polyimide.

19. (Original) The structure of claim 18 in which the second polymeric material is a polyimide.

20. (Currently amended) The structure of claim ~~19~~ 18 in which the substrate is an integrated circuit device and the second polymeric material is a polyepoxide.

21. (Original) The structure of claim 20 additionally comprising a chip carrier adjacent to the added layer.

22. (Original) The structure of claim 17 additionally comprising a layer of adhesion promoter between the silicon-oxide containing layer and the added layer.

23. (Original) The structure of claim 22 in which the adhesion promoter is selected from the group consisting of 3-amino-propyl-tri-ethoxy-silane, 3-glycidoxy-propyl-tri-methoxy-silane, N-(2-amino-ethyl)-3-amino-propyl-tri-ethoxy-silane, 3-amino-propyl-tri-methoxy-silane, N-(2-amino-ethyl)-3-amino-propyl-tri-methoxy-silane, 3-isocyanato-propyl-tri-ethoxy-silane, 10-amino-decyl-tri-methoxy-silane, 11-amino-undecyl-tri-methoxy-silane, n-propyl-tri-methoxy-silane, and phenyl-tri-methoxy-silane.

24. (Original) The structure of claim 21 in which the first polymeric material is a polyimide.

25.-35. (Cancelled)

36. (New) The structure of claim 20 in which the added layer additionally comprises solid particles of a thermally conductive and electrically insulating material.

37. (New) A composite structure comprising, in order:

a substrate;

a polymeric layer including a first polymeric material selected from the group consisting of polyimides, polyolefins, polyepoxides, polyurethanes, and polycarbonates;

a silicon-oxide containing layer; and

an added layer comprising polyepoxide and solid particles of a thermally conductive and electrically insulating material.

38. (New) The composite of claim 37 in which the first polymeric material is a polyimide.

39. (New) The composite structure of claim 38 in which the substrate is an integrated circuit device.